# Kulicke & Soffa Launches ConnX PlusPSTM Wire Bonder

(BUSINESS WIRE)--Mar. 9, 2012-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("K&S" or the "Company") today announced the formal launch of its ConnX Plus High Speed Wire Bonder. ConnX Plus is a second generation ball bonder under the successful *Power Series*TM. When compared to the previous generation, the ConnX Plus further increases net productivity in low pin count, discrete and cost performance markets.

Nelson Wong, Kulicke & Soffa's Vice President and Business Unit Executive, said, "By pairing the increased UPH of the ConnX Plus with additional new features, we are offering customers an impressive second generation of a successful *Power Series* ball bonder that showcases our technological leadership and further broadens our product offering. We continue to bolster our leadership position and stay ahead of the curve as we invest in and develop our R&D roadmap. Importantly, our customers will continue to benefit from Kulicke & Soffa's knowledge base, service history and innovative offerings that are not easily replicated or replaced."

In addition to features of the prior generation ConnX *PS*TM wire bonder, the ConnX Plus includes exciting new enhancements to help further increase efficiency and net productivity:

- Interactive Programmable Look Ahead Vision to ease first time set-up
- *Power Series* Xpress Loop to help increase the productivity of short wire applications
- Allows the integration of the optional Dual Mag Optics Kit to support stacked die applications in discrete and low pin count devices
- Field upgradable to the ConnX Plus LA*PS*TM in order to support an 87mm bondable area
- 10% higher UPH (Units Per Hour) over the first generation ConnX ball bonder.

The ConnX Plus will debut at the Semicon China show at the Shanghai New International Expo Centre from March 20-22, 2012.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor and LED assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions, adding die and wedge bonders and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

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